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(12) **United States Design Patent** (10) **Patent No.:** **US D902,164 S**  
**Kondo et al.** (45) **Date of Patent:** **\*\* Nov. 17, 2020**

(54) **INTEGRATED CIRCUIT CARD**

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(\*\*) Term: **15 Years**  
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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**

USPC ..... D10/80, 103; D13/110, 133, 139, 154, D13/173, 182; D14/217, 432, 433  
CPC ..... H01L 20/4238; H01L 23/528; H01L 29/0696; H01L 29/1095; H01L 29/417; H01L 29/66068; H01L 29/1608; H01L 29/7395; H01L 29/7802; H01L 29/66325; H01L 29/66348; H01L 29/161; H01L 29/162; H01L 29/163; H01L 29/164; H01L 29/165; H01L 29/166; H01L 29/167; H01L 21/18; H01L 21/19; H01L 21/20; H01L 21/21; H01L 21/22; H01L 21/23; H01L 21/24; H01L 21/25; H01L 21/26; H01L

(Continued)

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(57) **CLAIM**

The ornamental design for an integrated circuit card, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view 1 of an integrated circuit card showing our new design according to a first embodiment thereof,

FIG. 2 is a perspective view 2 thereof,

FIG. 3 is a front elevational view thereof,

FIG. 4 is a top plan view thereof,

FIG. 5 is a right side elevational view thereof,

FIG. 6 is a left side elevational view thereof,

FIG. 7 is a bottom plan view thereof, and

FIG. 8 is a rear elevational view thereof.

FIG. 9 is a perspective view 1 of an integrated circuit card showing our new design according to a second embodiment thereof,

FIG. 10 is a perspective view 2 thereof,

FIG. 11 is a front elevational view thereof,

FIG. 12 is a top plan view thereof,

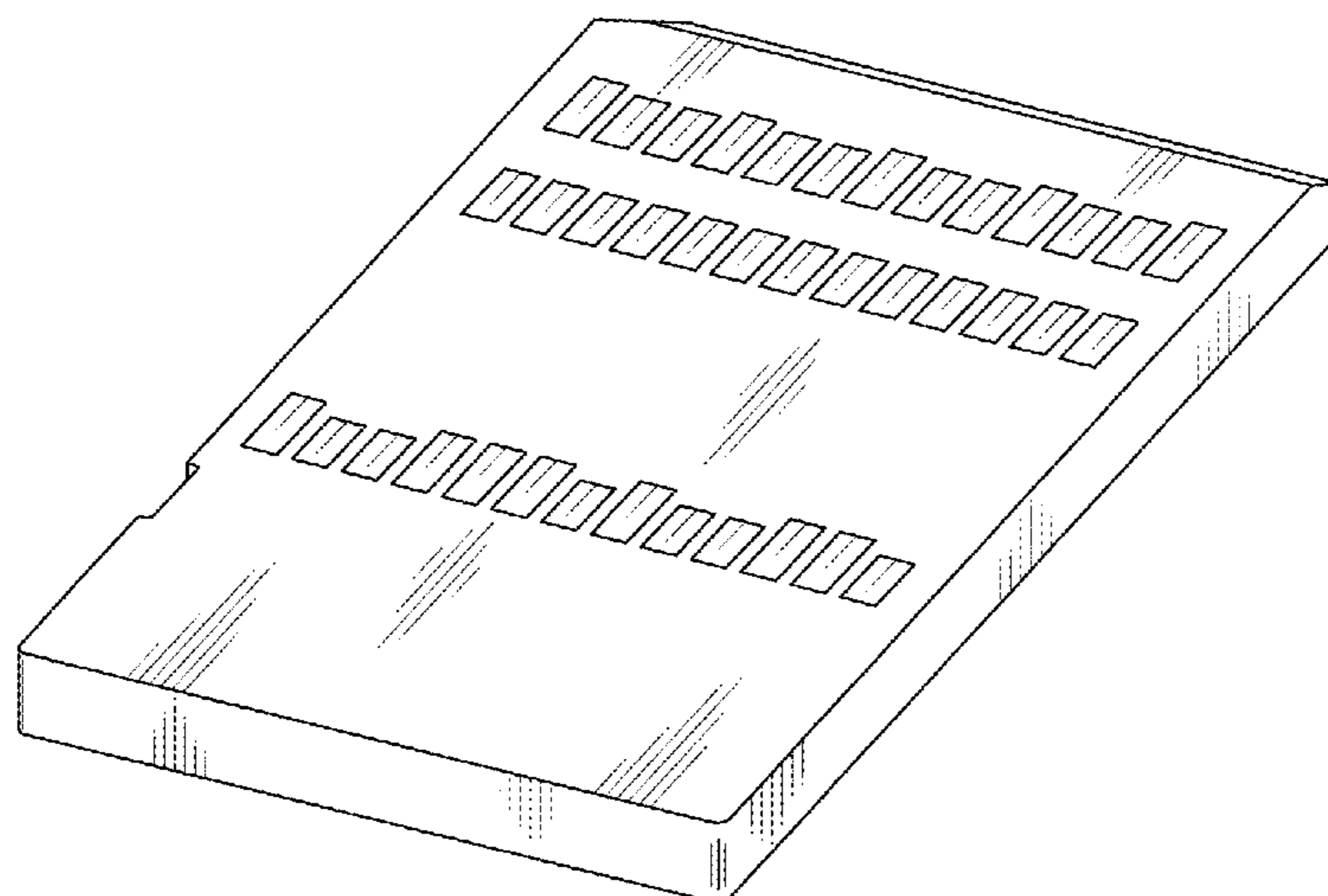
FIG. 13 is a right side elevational view thereof,

FIG. 14 is a left side elevational view thereof,

FIG. 15 is a bottom plan view thereof; and,

FIG. 16 is a rear elevational view thereof.

**1 Claim, 16 Drawing Sheets**



(58) **Field of Classification Search**  
 CPC ..... 21/27; H01L 21/28; H01L 21/29; H01L  
 21/30  
 See application file for complete search history.

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Fig. 1

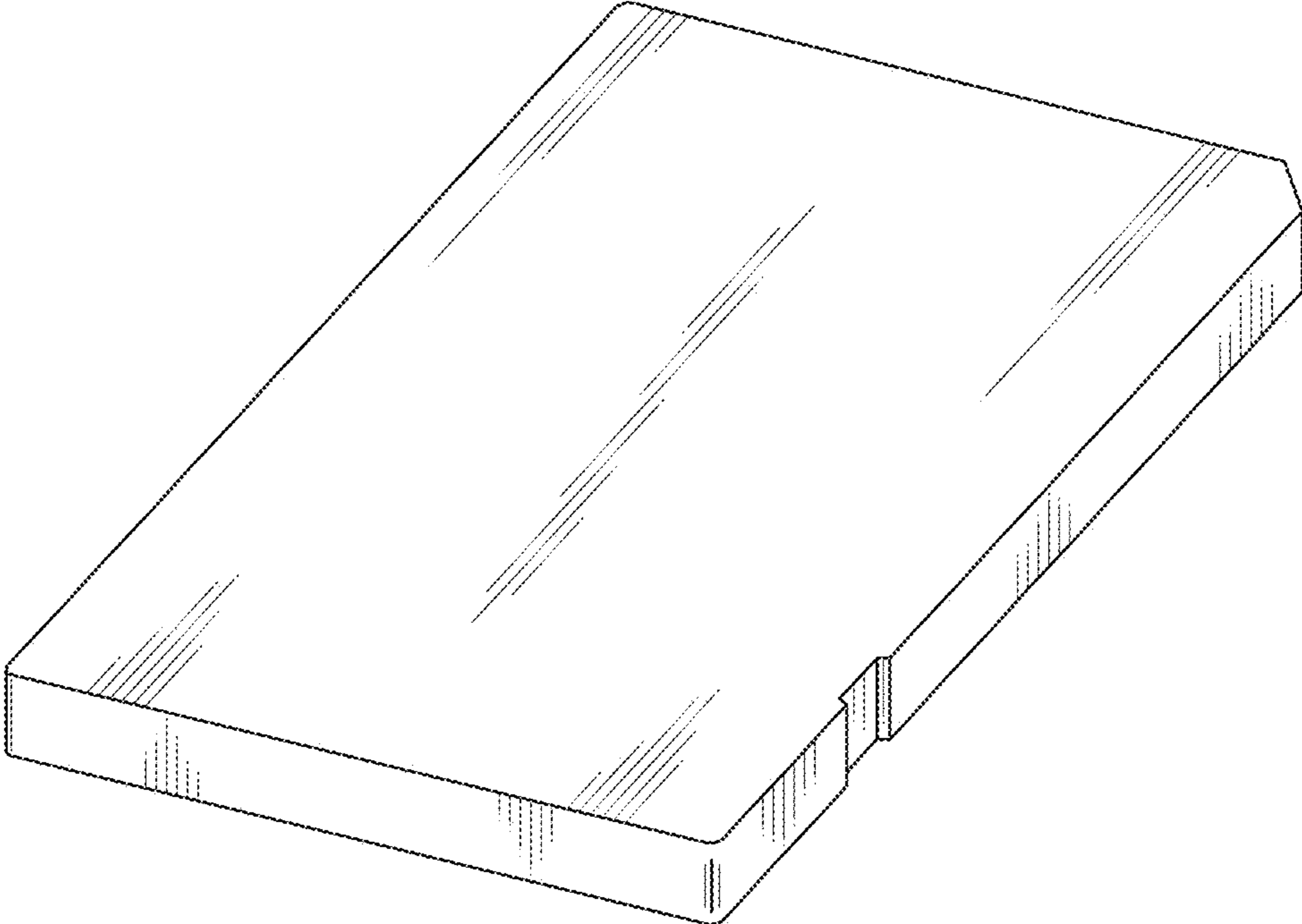


Fig. 2

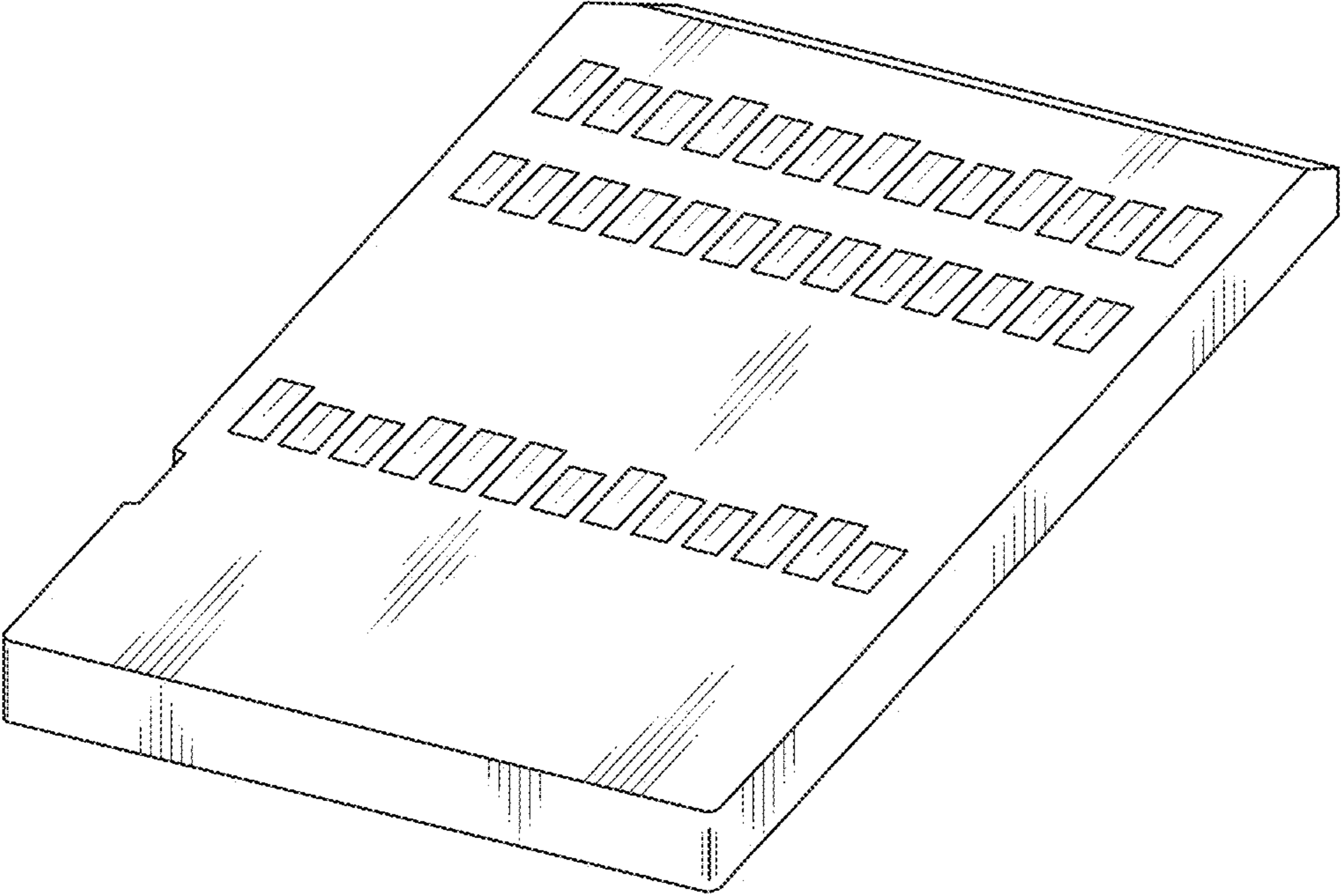


Fig. 3

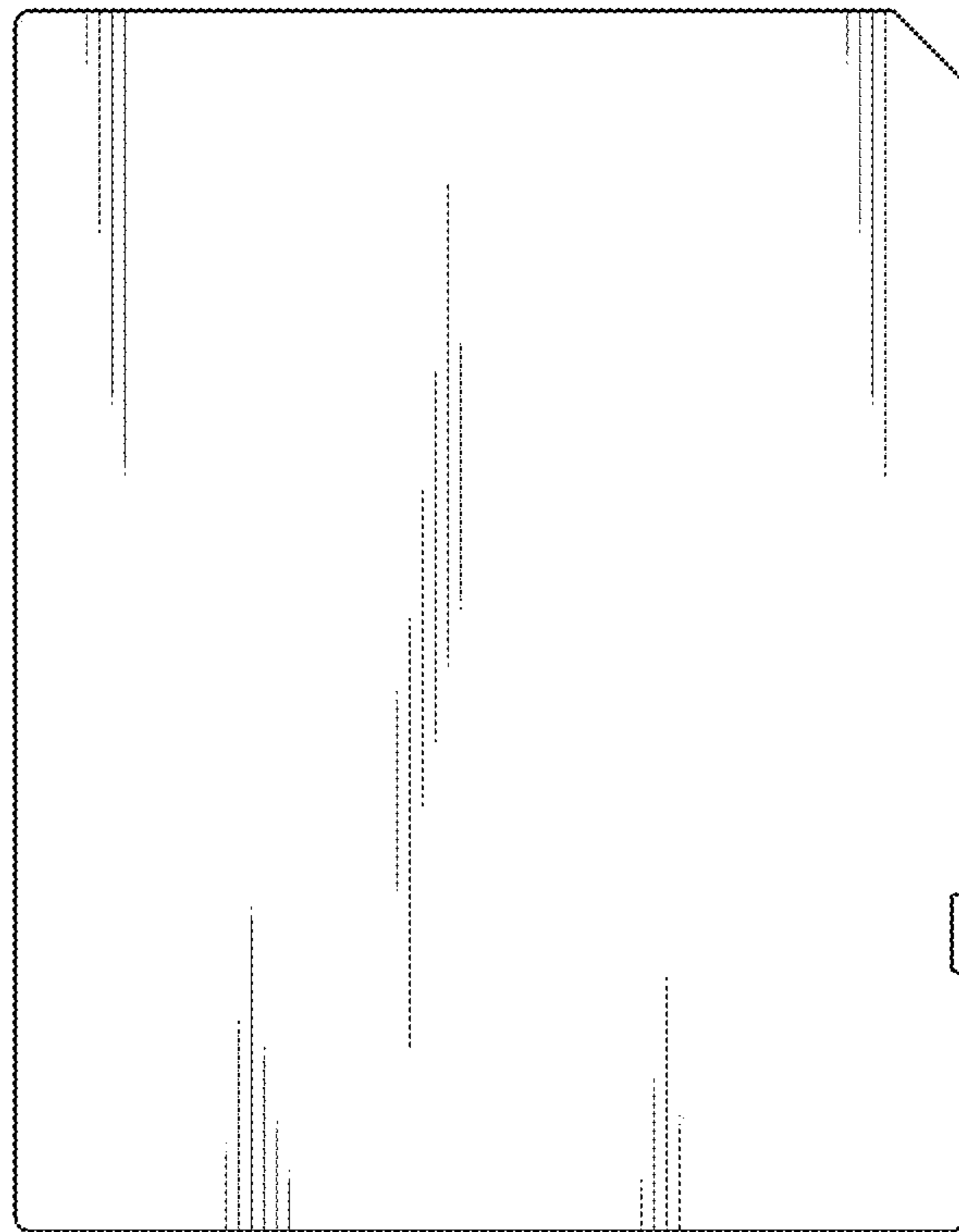


Fig. 4





Fig. 5

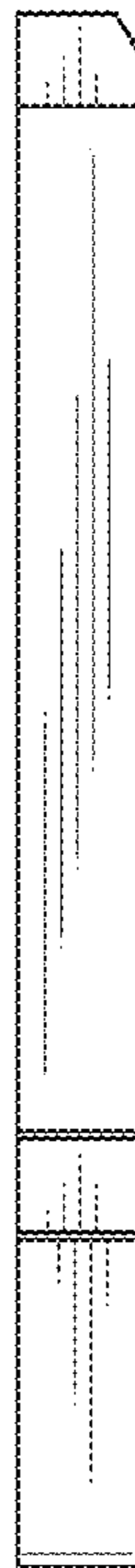


Fig. 6

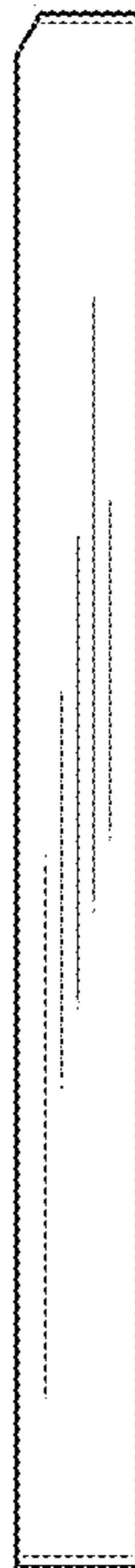




Fig. 7



Fig. 8

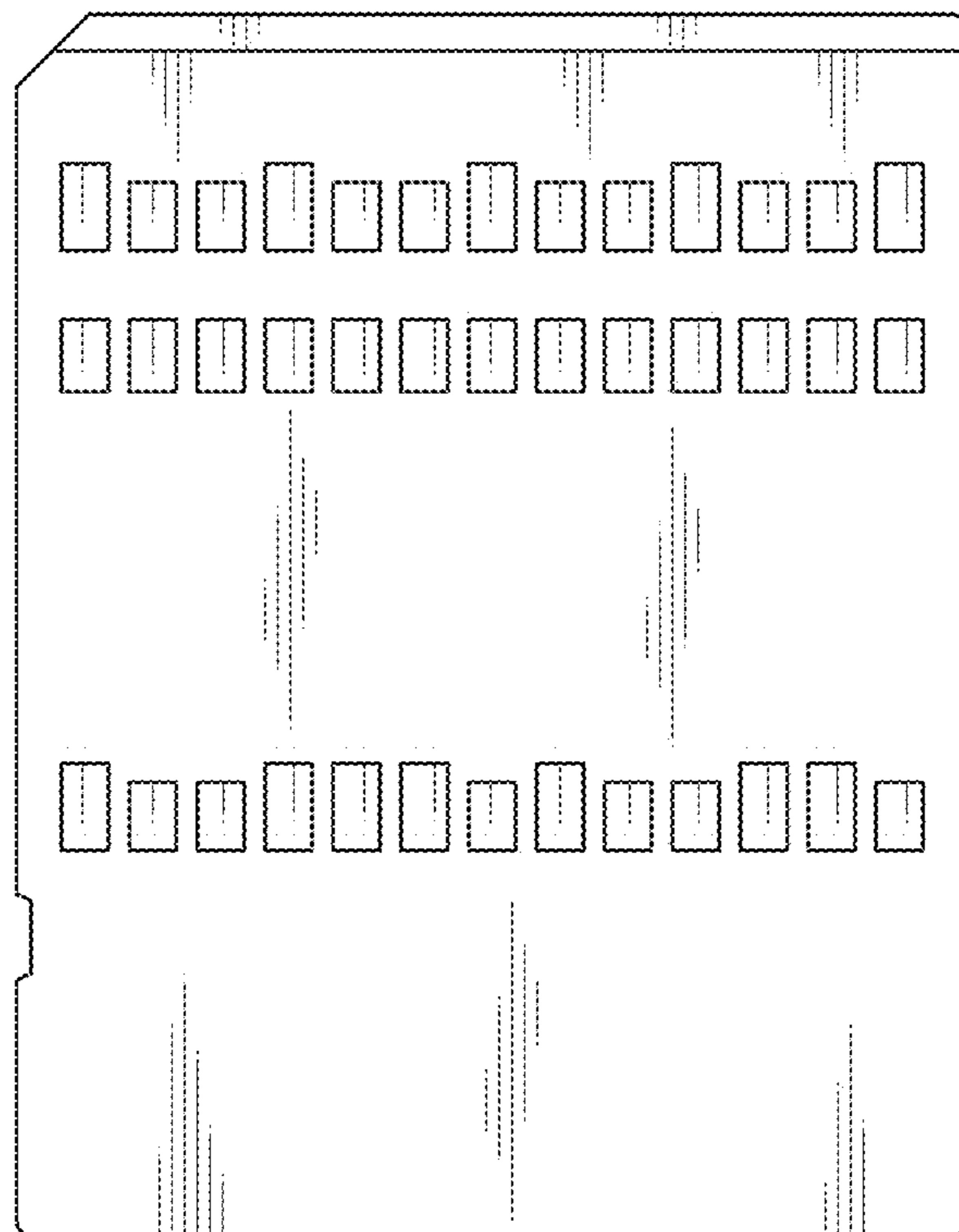


Fig. 9

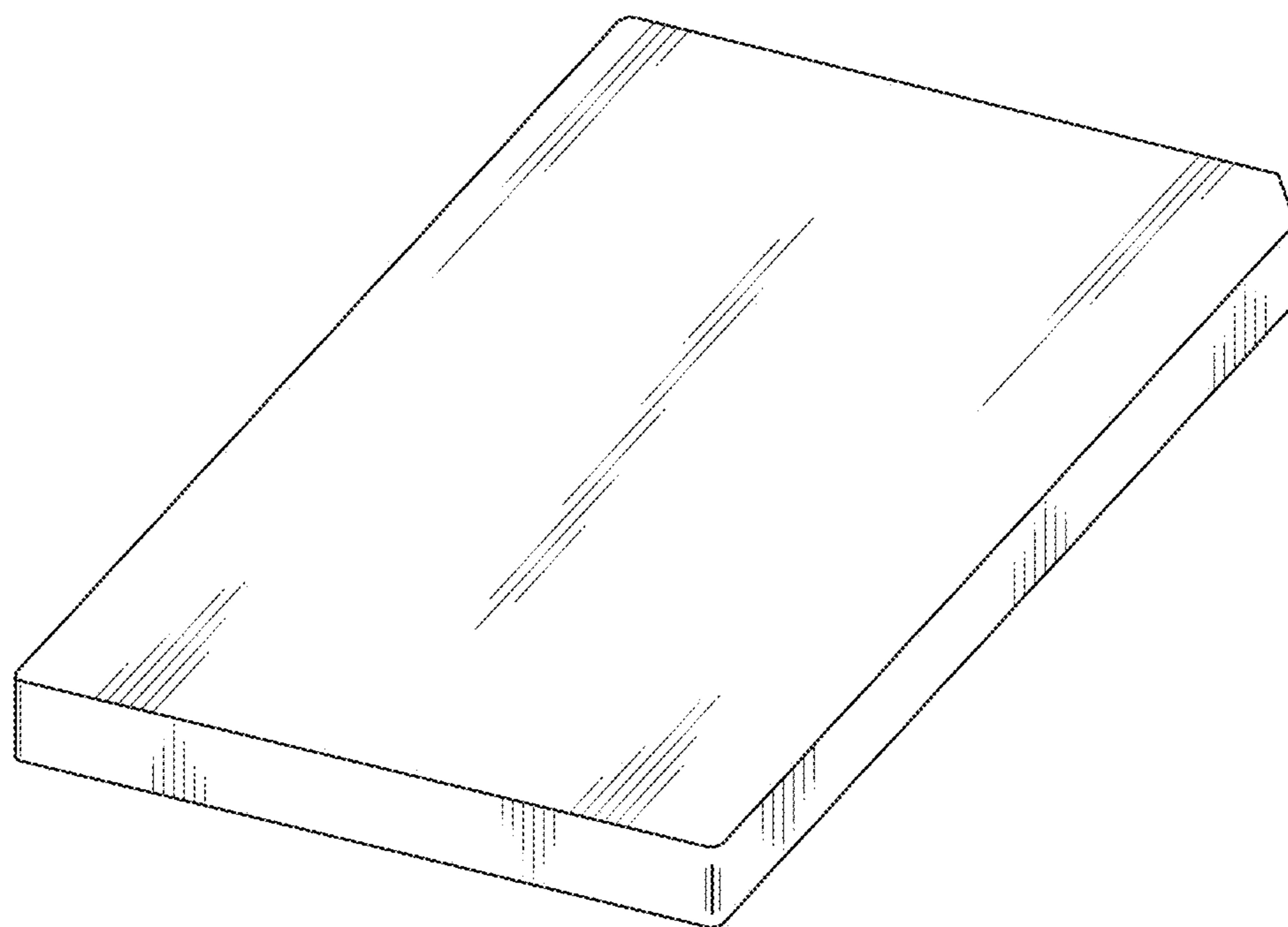


Fig. 10

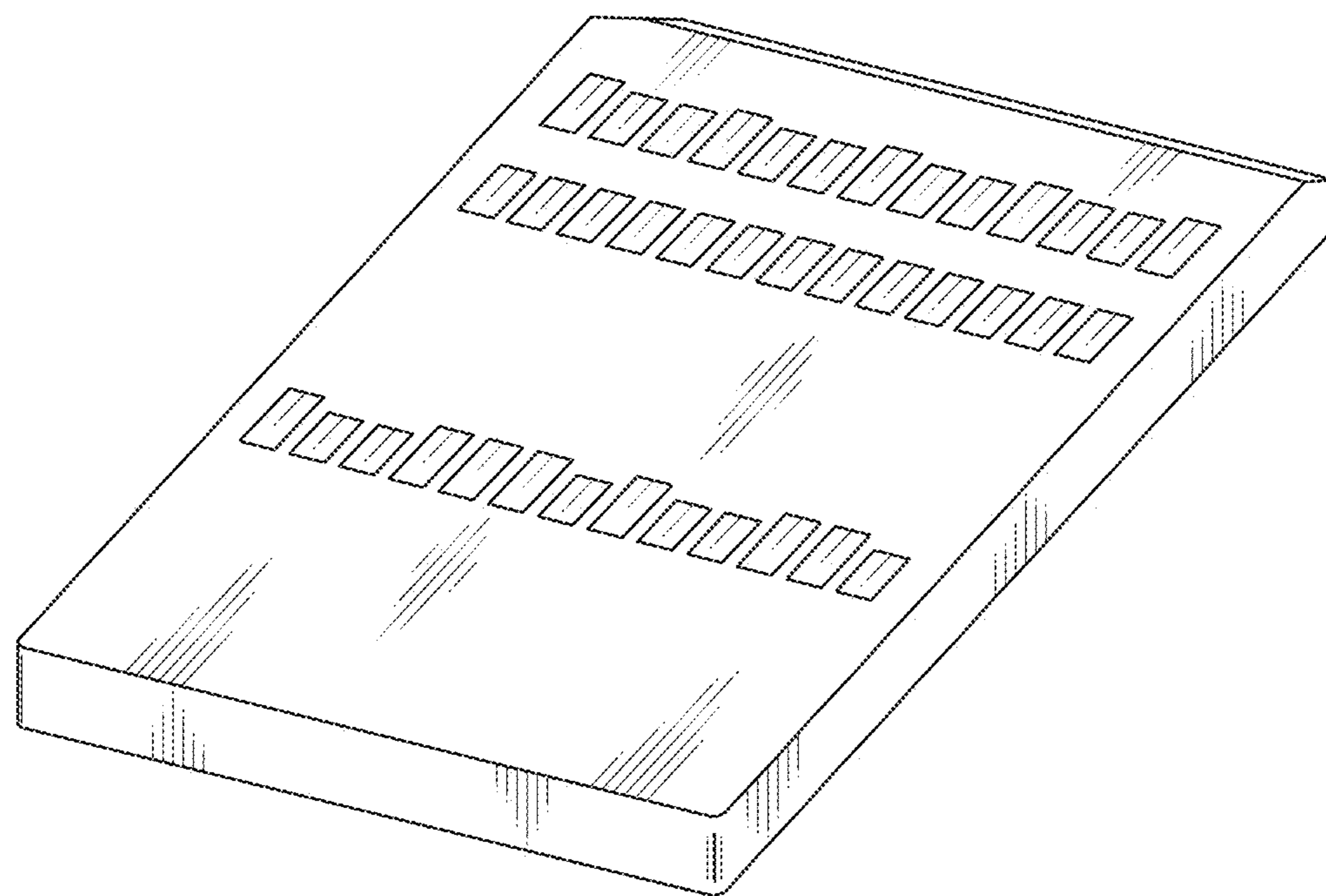


Fig. 11

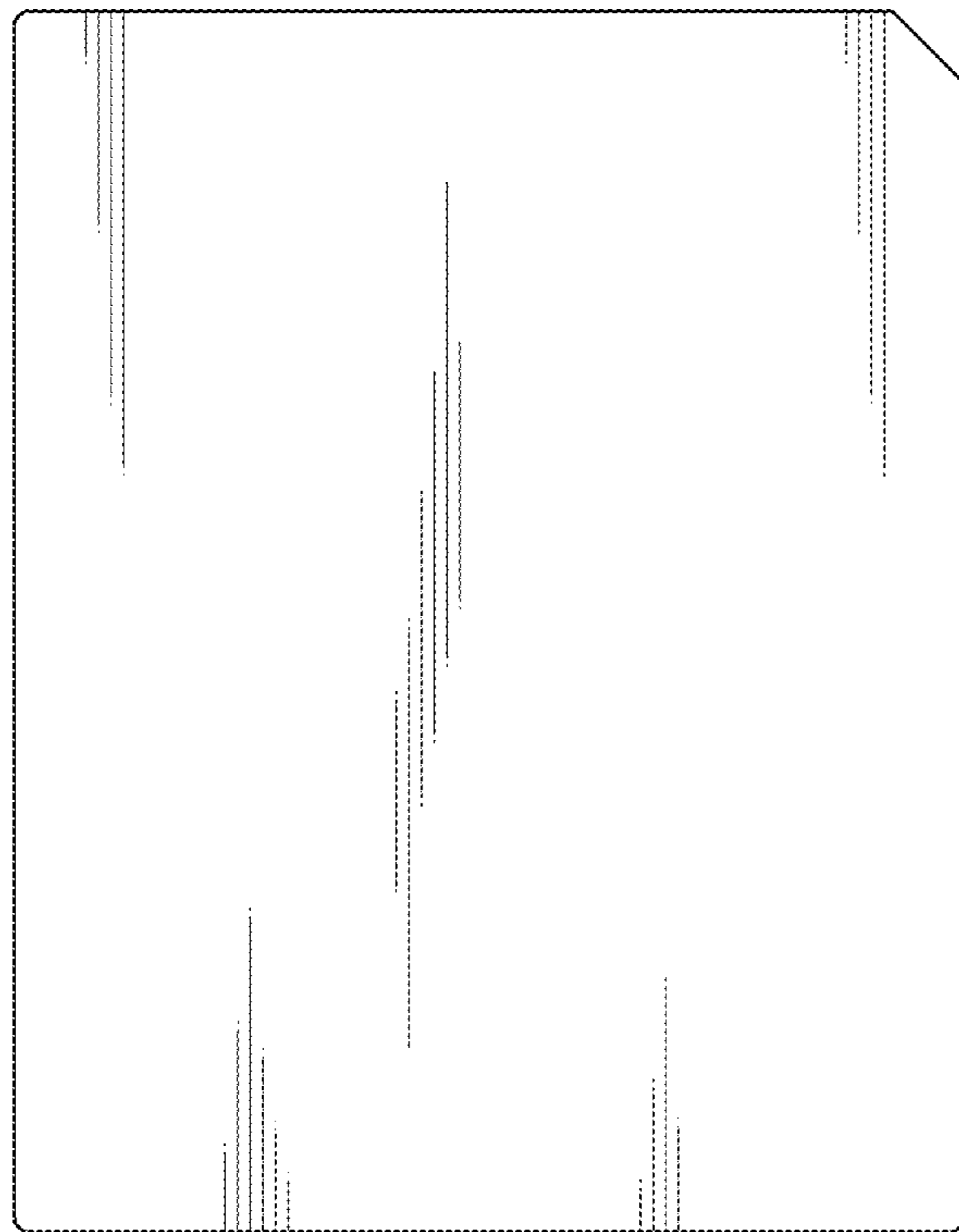


Fig. 12



Fig. 13





Fig. 14

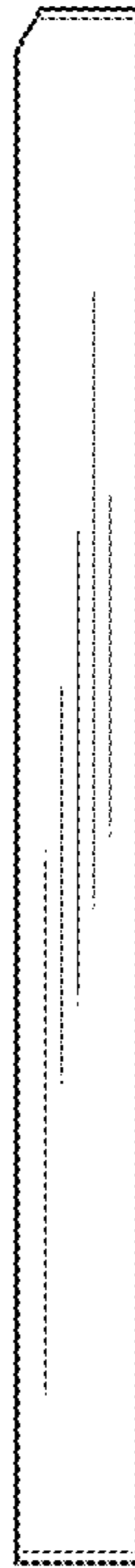


Fig. 15



Fig. 16

